

AMENDMENTS TO THE CLAIMS

1. (Previously canceled)
2. (Previously canceled)
3. (Previously canceled)
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13. (Previously canceled)
14. (Currently amended) A method for manufacturing flexible metallic fine structures on a thin base layer made of a flexible organic material, comprising:

 providing an auxiliary bearer made of a material that is at least largely transparent to laser radiation;

 applying the base layer onto the auxiliary bearer;

producing a flexible metallic fine structure on the base layer; and

detaching the base layer from the auxiliary bearer by projecting laser

radiation from a laser through the auxiliary bearer, which is reusable, onto the base layer.

15. (Previously Amended) A method according to claim 14, wherein the auxiliary bearer is of quartz glass and the laser is an excimer laser having a wavelength of 248nm for the laser radiation.

16. (Previously Amended) A method according to claim 14, wherein the auxiliary bearer is made of borosilicate glass and the laser is an excimer laser having a wavelength of 350nm for the laser radiation.

17. (Previously Amended) A method according to claim 14, which includes, before applying the base layer on the auxiliary bearer, applying an adhesive layer onto the auxiliary bearer.

18. (Previously Amended) A method according to claim 17, wherein the adhesive layer is made of titanium.

19. (Previously Amended) A method according to claim 18, wherein the adhesive layer is applied to the auxiliary bearer by sputtering.

20. (Previously Amended) A method according to claim 17, wherein the adhesive layer is applied by sputtering.

21. (Previously Amended) A method according to claim 14, wherein the base layer is applied in the form of a film.

22. (Previously Amended) A method according to claim 21, wherein the film is made of a thermostable polyamide.

23. (Previously Amended) A method according to claim 21, which includes applying a planarization layer of electrically insulating material on the base layer before producing the metallic fine structure.
24. (Previously Amended) A method according to claim 14, which includes applying an insulating layer on the fine metallic structure, forming a second layer of metallic fine structure on the insulating layer and then detaching the base layer from the auxiliary bearer.
25. (Previously Amended) A method according to claim 24, which includes forming holes in the insulating layer before applying the second layer of metallic fine structure and forming through-contacts between the second layer of metallic fine structure and the first layer of metallic fine structure while forming the second layer of metallic fine structure.
26. (Previously Amended) A method according to claim 24, which includes, before detaching the base layer from the auxiliary bearer, applying a passivation layer onto the second layer of metallic fine structure.
27. (Previously Amended) A sensor arrangement for the acquisition of fingerprints, said arrangement comprising a thin base layer, a first metallic fine structure on a surface of the base layer, an insulating layer on the first metallic fine structure, said insulating layer having holes, a second metallic fine structure on said insulating layer having through-contacts to the first metallic fine structure and a passivation layer covering the second metallic fine structure.